

Title (en)  
SEMICONDUCTOR CHIP ENCAPSULATION METHOD, DEVICE PRODUCED BY THIS METHOD AND ITS APPLICATION TO THREE DIMENSIONAL CHIP INTERCONNECTION.

Title (de)  
UNHÜLLUNGSVERFAHREN FÜR HALBLEITERCHIPS, DARAUS GEWONNENE TEILE UND VERWENDUNG FÜR DIE DREIDIMENSIONALE VERDRAHTUNG.

Title (fr)  
PROCEDE D'ENCAPSULATION DE PASTILLES SEMI-CONDUCTRICES, DISPOSITIF OBTENU PAR CE PROCEDE ET APPLICATION A L'INTERCONNEXION DE PASTILLES EN TROIS DIMENSIONS.

Publication  
**EP 0647357 A1 19950412 (FR)**

Application  
**EP 94913654 A 19940415**

Priority  
• FR 9400427 W 19940415  
• FR 9304962 A 19930427

Abstract (en)  
[origin: WO9425987A1] According to the method of the invention, conductive leads are directly wired onto a semiconductor wafer carrying a large number of chips, the wafer is bonded to a resilient film and cut to separate each chip, after which the film is stretched to space the chips; the totality of the chips and leads are then held in an insulating material such as a polymerizable resin, and, after polishing, metal plating is applied over the leads to connect them to the sides of the chips; the assembly is then cut in order to separate the chips.

IPC 1-7  
**H01L 25/065**; **H01L 23/49**

IPC 8 full level  
**H01L 21/301** (2006.01); **H01L 21/56** (2006.01); **H01L 23/482** (2006.01); **H01L 23/49** (2006.01); **H01L 25/065** (2006.01); **H01L 25/10** (2006.01); **H01L 25/11** (2006.01); **H01L 25/18** (2006.01)

CPC (source: EP)  
**H01L 23/4824** (2013.01); **H01L 24/24** (2013.01); **H01L 24/96** (2013.01); **H01L 24/97** (2013.01); **H01L 25/0657** (2013.01); **H01L 24/48** (2013.01); **H01L 2224/02333** (2013.01); **H01L 2224/02371** (2013.01); **H01L 2224/04105** (2013.01); **H01L 2224/1134** (2013.01); **H01L 2224/24137** (2013.01); **H01L 2224/48091** (2013.01); **H01L 2224/48472** (2013.01); **H01L 2225/06524** (2013.01); **H01L 2225/06551** (2013.01); **H01L 2225/06589** (2013.01); **H01L 2924/00013** (2013.01); **H01L 2924/00014** (2013.01); **H01L 2924/01013** (2013.01); **H01L 2924/01015** (2013.01); **H01L 2924/01029** (2013.01); **H01L 2924/01058** (2013.01); **H01L 2924/01061** (2013.01); **H01L 2924/01078** (2013.01); **H01L 2924/01079** (2013.01); **H01L 2924/14** (2013.01); **H01L 2924/3025** (2013.01)

Citation (search report)  
See references of WO 9425987A1

Designated contracting state (EPC)  
BE DE FR GB IT

DOCDB simple family (publication)  
**WO 9425987 A1 19941110**; EP 0647357 A1 19950412; FR 2704690 A1 19941104; FR 2704690 B1 19950623; JP H07509104 A 19951005

DOCDB simple family (application)  
**FR 9400427 W 19940415**; EP 94913654 A 19940415; FR 9304962 A 19930427; JP 52394194 A 19940415